

3. (Unchanged) The cooling assembly of claim 2, wherein the alternate passage includes a conduit in communication with the isolation assembly.

4. (Unchanged) The cooling assembly of claim 1, and further comprising a heat sink operably coupled to the first component.

5. (Unchanged) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

6. (Unchanged) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

32. (New) The cooling assembly of claim 4, wherein the heat sink comprises a passive heat sink.

33. (New) The cooling assembly of claim 1, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

34. (New) A cooling assembly for at least one board, the at least one board suitable for accepting a plurality of components including a first component, the cooling assembly comprising:

a passage;

a fan suitable for passing air through the passage; and

an isolation assembly for generally enclosing heat generated from the first

component, wherein the first component is enclosed within the isolation

assembly, the isolation assembly in communication with the passage, and

wherein the passage is separate from another heat-sensitive component

within the computer case.

35. (New) The cooling assembly of claim 34, and further comprising an alternate passage in communication with the isolation assembly.

36. (New) The cooling assembly of claim 35, wherein the alternate passage includes a conduit in communication with the isolation assembly.

37. (New) The cooling assembly of claim 34, and further comprising a heat sink operably coupled to the first component.

38. (New) The cooling assembly of claim 34, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

39. (New) The cooling assembly of claim 34, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

40. (New) The cooling assembly of claim 37, wherein the heat sink comprises a passive heat sink.

41. (New) The cooling assembly of claim 34, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

REMARKS

Applicant has reviewed and considered the Office Action mailed on May 8, 2002, and the references cited therewith.

Claim 1 is amended and claims 32-41 are added. Claims 1-6 and 32-41 are now pending in this application. No new matter has been added by these amendments. Applicant respectfully requests reconsideration and allowance of all claims in view of the amendments above and the remarks that follow.